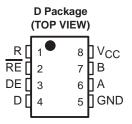
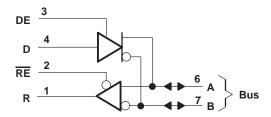
- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication
- **Extended Temperature Performance of** -40°C to 125°C and -55°C to 125°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product Change Notification**
- Qualification Pedigree†
- High-Speed Low-Power LinBiCMOS™ Circuitry Designed for Signaling Rates[‡] Up to 30 Mbps
- **Bus-Pin ESD Protection Exceeds 12-kV HBM**
- **Compatible With ANSI Standard** TIA/EIA-485-A and ISO 8482:1987(E)
- Low Skew
- **Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments**
- **Low Disabled Supply Current** Requirements . . . 700 µA Maximum
- Common-Mode Voltage Range of -7 V to 12 V
- **Thermal-Shutdown Protection**
- **Driver Positive and Negative Current** Limiting
- **Open-Circuit Fail-Safe Receiver Design**
- Receiver Input Sensitivity . . . ±200 mV Max
- Receiver Input Hysteresis . . . 50 mV Typ
- Glitch-Free Power-Up and Power-Down **Protection**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

\$\frac{1}{2}\$ Signaling rate by TIA/EIA-485-A definition restrict transition times to 30% of the bit length, and much higher signaling rates may be achieved without this requirement as displayed in the TYPICAL CHARACTERISTICS of this device.



logic diagram (positive logic)



Function Tables

DRIVER

| INPUT | ENABLE | ОПТІ | PUTS |
|-------|--------|------|------|
| D | DE | Α | В |
| Н | Н | Н | L |
| L | Н | L | Н |
| X | L | Z | Z |
| Open | Н | Н | L |

RECEIVER

| DIFFERENTIAL INPUTS | ENABLE | OUTPUT |
|--|--------|--------|
| V _A -V _B | RE | R |
| V _{ID} ≥ 0.2 V | L | Н |
| $-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$ | L | ? |
| V _{ID} ≤ −0.2 V | L | L |
| X | Н | Z |
| Open | L | Н |

H = high level,L = low level,? = indeterminate,

X = irrelevant.Z = high impedance (off)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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description/ordering information

The SN65LBC176A-EP differential bus transceiver is a monolithic, integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. The SN65LBC176A-EP is designed for balanced transmission lines and is compatible with ANSI standard TIA/EIA-485-A and ISO 8482. The SN65LBC176A-EP offers improved switching performance over its predecessors without sacrificing significantly more power.

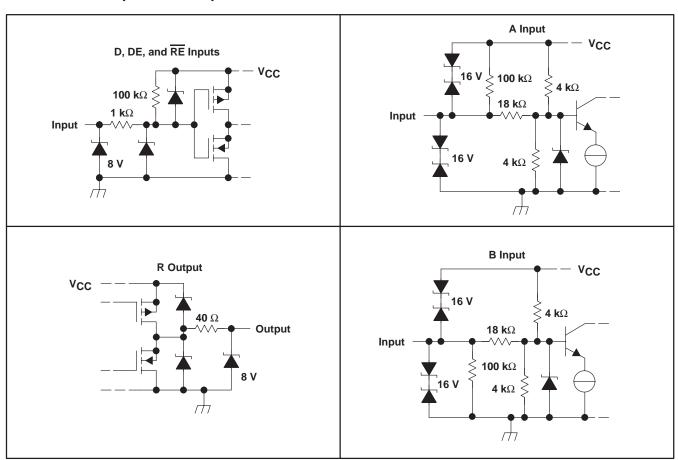
The SN65LBC176A-EP combines a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can externally connect together to function as a direction control. The driver differential outputs and the receiver differential inputs connect internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus whenever the driver is disabled or V_{CC} = 0. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications. Low device supply current can be achieved by disabling the driver and the receiver.

ORDERING INFORMATION

| TA | PACKAGE [†] | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|----------------------|---------------|--------------------------|---------------------|
| -40°C to 125°C | SOIC - D | Tape and Reel | SN65LBC176AQDREP | 176AEP |
| -55°C to 125°C | SOIC - D | Tape and Reel | SN65LBC176AMDREP | 176MEP |

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.

schematics of inputs and outputs





absolute maximum ratings†

| Supply voltage, V _{CC} (see Note 1) | 0.3 V to 6 V |
|--|----------------------------------|
| Voltage range at any bus terminal (A or B) | –10 V to 15 V |
| Input voltage, V _I (D, DE, R, or RE) | 0.3 V to V _{CC} + 0.5 V |
| Electrostatic discharge: Bus terminals and GND, Class 3, A: (see Note 2) | |
| Bus terminals and GND, Class 3, B: (see Note 2) | 400 V |
| All terminals, Class 3, A: | 4 kV |
| All terminals, Class 3, B: | 400 V |
| Continuous total power dissipation (see Note 3) | See Dissipation Rating Table |
| Storage temperature range, T _{stq} (see Note 4) | 65°C to 150°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

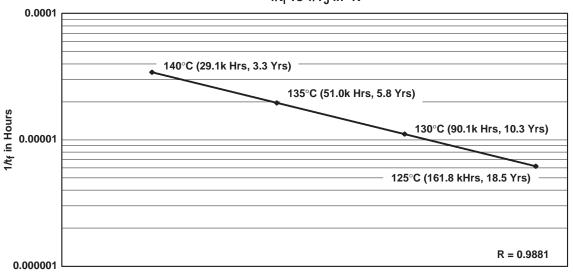
- NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.
 - 2. The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.
 - 3. Tested in accordance with MIL-STD-883C, Method 3015.7
 - 4. Long-term, high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

DISSIPATION RATING TABLE

| PACKAGE | $T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING | DERATING FACTOR‡ ABOVE T _A = 25°C | T _A = 70°C POWER RATING | T _A = 85°C POWER RATING | T _A = 125°C POWER RATING |
|---------|--|---|---------------------------------------|---------------------------------------|--|
| D | 725 mW | 5.8 mW/°C | 464 mW | 377 mW | 145 mW |

[‡] This is the inverse of the junction-to-ambient thermal resistance when the board is mounted and with no air flow.

OPERATING LIFE DERATING TABLE – SN65LBC176AMDREP $1/t_{\rm f}$ vs $1/T_{\rm J}$ in $^{\circ}$ K



1/T_J in °K

NOTES: A. See the data sheet for absolute maximum and maximum recommended operating conditions.

- B. Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).
- C. Attached enhanced plastic product disclaimer applies.



SN65LBC176A-EP **DIFFERENTIAL BUS TRANSCEIVER**

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recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|--|-----------------|------|-----|------|------|
| Supply voltage, V _{CC} | | 4.75 | 5 | 5.25 | V |
| Voltage at any bus terminal (separately or common mode |) ViorVio | | | 12 | V |
| Voltage at any bus terminal (separately or common mode | 7), VI OI VIC | -7 | | | V |
| High-level input voltage, VIH (output recessive) | D, DE, and RE | 2 | | Vcc | V |
| Low-level input voltage, V _{IL} (output dominant) | D, DE, and RE | 0 | | 0.8 | V |
| Differential input voltage, V _{ID} (see Note 5) | | -12§ | | 12 | V |
| | Driver | -60 | | | |
| High-level output current, IOH | Receiver | -8 | | | mA |
| Law book and and an extend to | Driver | | | 60 | 4 |
| Low-level output current, IOL | Receiver | | | 8 | mA |
| On another force shall be somewhat T | SN65LBC176AQ-EP | -40 | | 125 | 00 |
| Operating free-air temperature, T _A | SN65LBC176AM-EP | -55 | | 125 | °C |

[§] The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet. NOTE 5. Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

| | PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------|--|---|---------------------------------------|------|-----|--------|------|
| VIK | Input clamp voltage | $I_{I} = -18 \text{ mA}$ | -1.5 | -0.8 | | V | |
| | | I _O = 0 | | 1.5 | 4 | 6 | |
| VOD | Differential output voltage | $R_L = 54 \Omega$, | See Figure 1 | 0.9 | 1.5 | 6 | V |
| | | $V_{test} = -7 \text{ V to}$ | 12 V, See Figure 2 | 0.9 | 1.5 | 6 | |
| Δ V _{OD} | Change in magnitude of differential output voltage | See Figure 1 ar | nd Figure 2 | -0.2 | | 0.2 | V |
| V _{OC} (SS) | Steady-state common-mode output voltage | See Figure 1 | 1.8 | 2.4 | 3 | V | |
| Δ V _{OC} (SS) | Change in steady-state common-mode output voltage† | See Figure 1 | -0.2 | | 0.2 | V | |
| loz | High-impedance output current | See receiver input currents | | | | | |
| lіН | High-level enable input current | V _I = 2 V | V _I = 2 V | | | | μА |
| I _{IL} | Low-level enable input current | V _I = 0.8 V | | -100 | | | μА |
| los | Short-circuit output current | $-7 \text{ V} \le \text{V}_{\text{O}} \le 12 \text{ V}$ | | -250 | ±70 | 250 | mA |
| | | .,, | Receiver disabled and driver enabled | | 5 | 9 | |
| ICC | Supply current | $V_I = 0$ or V_{CC} , | Receiver disabled and driver disabled | | 0.4 | 0.7 mA | |
| | | | Receiver enabled and driver enabled | | 8.5 | 15 | |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



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driver switching characteristics over recommended operating conditions (unless otherwise noted)

| | PARAMETER | TEST CONDITIONS | MIN | TYP [†] | MAX | UNIT |
|--------------------|---|---|-----|------------------|-----|------|
| ^t PLH | Propagation delay time, low-to-high level output | | 2 | | 12 | |
| tPHL | Propagation delay time, high-to-low level output |] | 2 | | 12 | |
| t _{sk(p)} | Pulse skew (tpLH - tpHL) | $R_L = 54 \Omega$, $C_L = 50 pF$, See Figure 3 | | | 2 | ns |
| t _r | Differential output signal rise time | occ riguic o | 1.2 | | 11 | |
| tf | Differential output signal fall time | | 1.2 | | 11 | |
| ^t PZH | Propagation delay time, high-impedance to high-level output | R_L = 110 Ω, See Figure 4 | | | 22 | ns |
| tPZL | Propagation delay time, high-impedance to low-level output | R_L = 110 $Ω$, See Figure 5 | | | 25 | ns |
| tPHZ | Propagation delay time, high-level to high-impedance output | R_L = 110 $Ω$, See Figure 4 | | | 22 | ns |
| tPLZ | Propagation delay time, low-level to high-impedance output | R_L = 110 Ω, See Figure 5 | | | 22 | ns |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

| | PARAMETER | | TEST CONDIT | IONS | MIN | TYP [†] | MAX | UNIT |
|------------------|---|--|-------------------------------------|------------------------|------|------------------|-----|------|
| V _{IT+} | Positive-going input threshold voltage | $I_O = -8 \text{ mA}$ | | | | | 0.2 | V |
| VIT- | Negative-going input threshold voltage | I _O = 8 mA | | | -0.2 | | | V |
| V _{hys} | Hysteresis voltage (V _{IT+} - V _{IT-}) | Ŭ | | | | 50 | | mV |
| ٧ıK | Enable-input clamp voltage | I _I = –18 mA | | | -1.5 | -0.8 | | V |
| Vон | High-level output voltage | $V_{ID} = 200 \text{ mV},$ | $I_{OH} = -8 \text{ mA},$ | See Figure 6 | 4 | 4.9 | | V |
| VOL | Low-level output voltage | $V_{ID} = 200 \text{ mV},$ | $I_{OL} = 8 \text{ mA},$ | See Figure 6 | | 0.1 | 8.0 | V |
| loz | High-impedance-state output current | $V_O = 0$ to V_{CC} | | | -10 | | 10 | μΑ |
| | | V _{IH} = 12 V, | V _{CC} = 5 V | | | 0.4 | 1 | |
| | Bus land summed | V _{IH} = 12 V, | VCC = 0 | Other terror of OV | | 0.5 | 1 | 4 |
| 11 | Bus input current | $V_{IH} = -7 V$, | V _{CC} = 5 V | Other input at 0 V | -0.8 | -0.4 | | mA |
| | | $V_{IH} = -7 V$, | VCC = 0 |] | -0.8 | -0.3 | | |
| lн | High-level enable-input current | V _{IH} = 2 V | V _{IH} = 2 V | | | | | μΑ |
| IIL | Low-level enable-input current | V _{IL} = 0.8 V | | | -100 | | | μΑ |
| | | .,, | Receiver enable | ed and driver disabled | | 4 | 7 | |
| ICC | Supply current | V _I = 0 or V _{CC} , No load Receiver disabled and driver disabled | | | 0.4 | 0.7 | mA | |
| | | 140 1000 | Receiver enabled and driver enabled | | | 8.5 | 15 | |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



SN65LBC176A-EP DIFFERENTIAL BUS TRANSCEIVER

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receiver switching characteristics over recommended operating conditions (unless otherwise noted)

| | PARAMETER | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|--------------------|-------------------------------------|---|-----|------|-----|------|
| t _{PLH} | Propagation delay time, output↑ | | 7 | | 30 | ns |
| tPHL | Propagation delay time, output↓ | V _{ID} = −1.5 V to 1.5 V, See Figure 7 | 7 | | 30 | ns |
| t _{sk(p)} | Pulse skew (tpHL -tpLH) | , | | | 6 | ns |
| t _r | Rise time, output | O Firm. 7 | | | 5 | ns |
| t _f | Fall time, output | See Figure 7 | | | 5 | ns |
| tPZH | Output enable time to high level | | | | 50 | ns |
| tPZL | Output enable time to low level | C _L = 10 pF, See Figure 8 | | | 50 | ns |
| ^t PHZ | Output disable time from high level | | | | 60 | ns |
| tPLZ | Output disable time from low level | | | | 40 | ns |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



PARAMETER MEASUREMENT INFORMATION

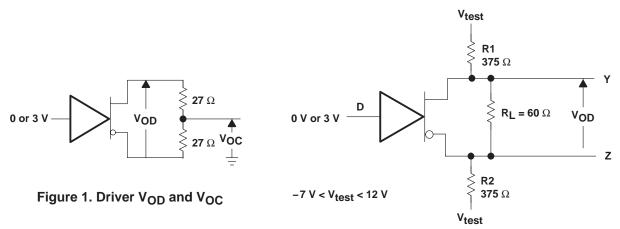
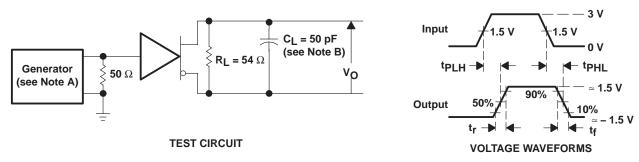
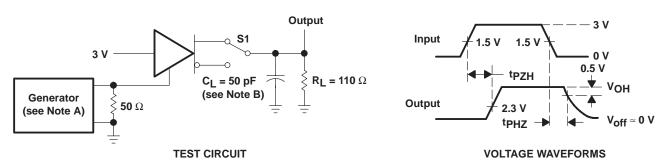


Figure 2. Driver V_{OD3}



- NOTES: D. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - E. C_L includes probe and jig capacitance.

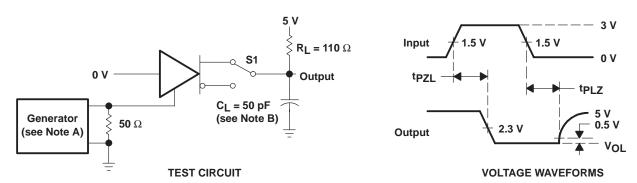
Figure 3. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. C_L includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. C_L includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

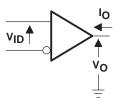
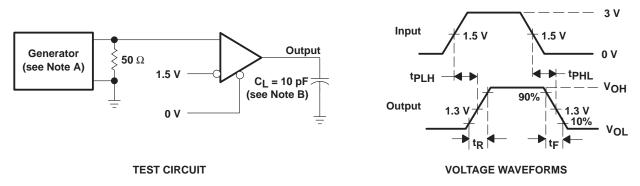


Figure 6. Receiver VOH and VOL

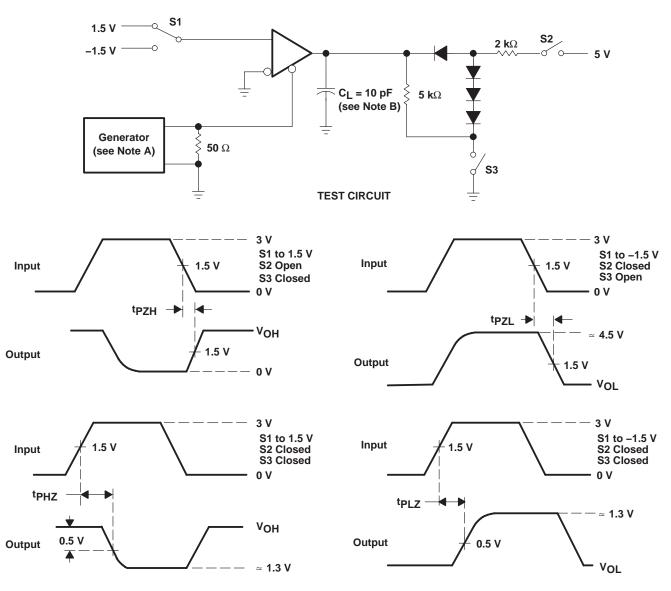


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 8 ns, $t_f \leq$ 8 ns, $t_f \leq$ 9 ns, t_f
 - B. C_L includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$

B. CL includes probe and jig capacitance.

Figure 8. Receiver Test Circuit and Voltage Waveforms

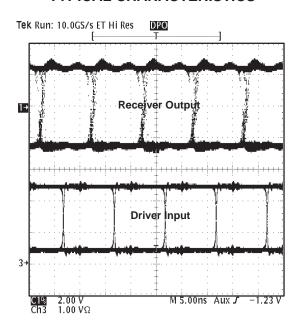




Figure 9. Typical Waveform of Non-Return-To-Zero (NRZ), Pseudorandom Binary Sequence (PRBS) Data at 100 Mbps Through 15m, of CAT 5 Unshielded Twisted Pair (UTP) Cable

TIA/EIA-485-A defines a maximum signaling rate as that in which the transition time of the voltage transition of a logic-state change remains less than or equal to 30% of the bit length. Transition times of greater length perform quite well, even though they do not meet the standard by definition.



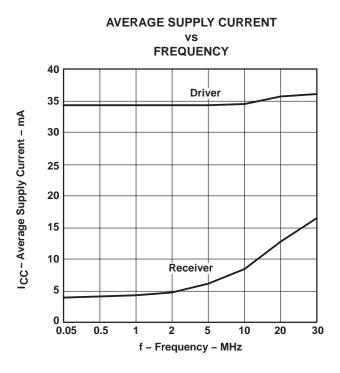


Figure 10

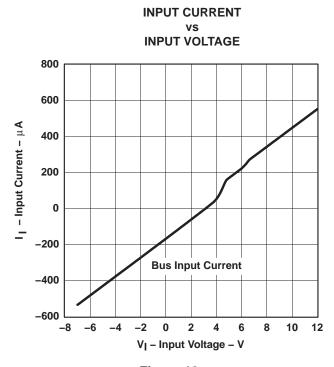


Figure 12

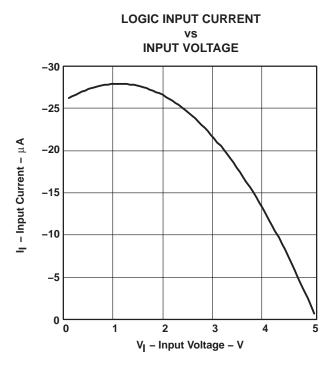


Figure 11

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

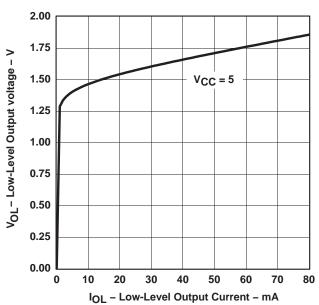


Figure 13

DRIVER HIGH-LEVEL OUTPUT VOLTAGE HIGH-LEVEL OUTPUT CURRENT 5 4.5 VOH - High-Level Output Voltage - V V_{CC} = 5.25 V 3.5 3 2.5 $V_{CC} = 5 V$ 2 $V_{CC} = 4.75 V$ 1.5 0.5 -40 -50 -60 -30 I_{OH} - High-Level Output Current - (mA)

Figure 14

RECEIVER PROPAGATION TIME **CASE TEMPERATURE** 13.8 13.7 13.6 TPHL Receiver (ns) 13.5 13.4 13.3 13.2 13.1 13 12.9 _40 25 70 Case Temperature - C Figure 16

DRIVER DIFFERENTIAL OUTPUT VOLTAGE vs

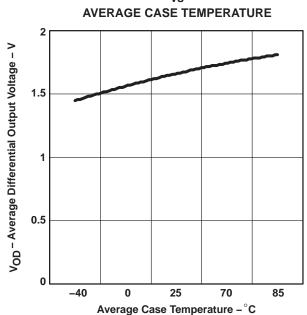


Figure 15

DRIVER PROPAGATION DELAY TIME

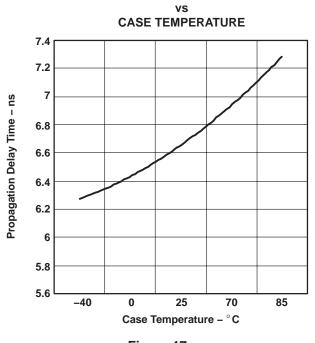


Figure 17

DRIVER OUTPUT CURRENT vs SUPPLY VOLTAGE

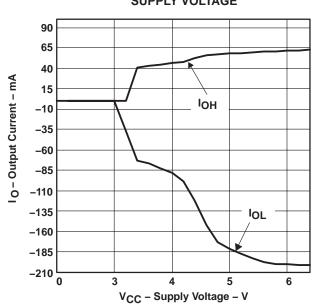


Figure 18





.com 5-Feb-2007

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|---------------------------|------------------|------------------------------|
| SN65LBC176AMDREP | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN65LBC176AQDREP | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| V62/03671-01XE | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| V62/03671-02XE | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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